

ABSTRACT OF THE DISCLOSURE

An image-capturing semiconductor device is provided with a simplified constitution and by means of fewer steps than conventional techniques. In a semiconductor device which is
5 packaged at substantially identical outer dimensions to the outer dimensions of a first semiconductor chip, first pads serving as electrode pads are formed along a main surface of the semiconductor chip so as to be electrically connected to a circuit element provided on the semiconductor chip. A sensor
10 portion is formed on the main surface such that a light-receiving surface thereof is exposed. A glass plate for transmitting incoming light to the sensor portion is formed in a position covering the light-receiving surface of the sensor portion. A wiring layer is formed so as to extend over the main surface
15 of the first semiconductor chip and such that one end thereof is connected to the first pads. Solder balls are electrically connected to the first pads via the wiring layer.